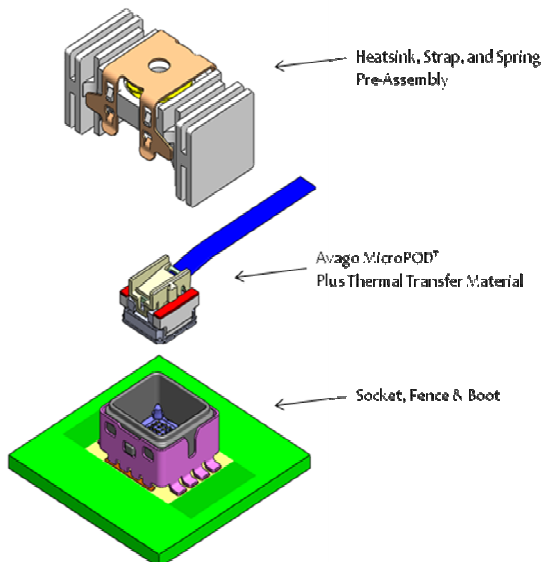


The new snap-and-go micro cLGA[®] integrated socket is [™] embedded parallel optics transceiver products. The socket integrates a thermal heat sink with the PCB connector retention mechanism needed with Avago's MicroPOD LGA electrical interface. More importantly, this new integrated socket significantly simplifies the board design and assembly while preserving the industry's smallest socket footprint.



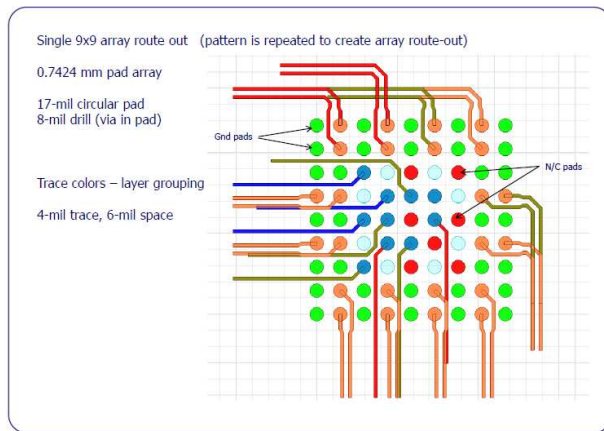
Amphenol's patented cLGA[®] product design features an E shaped beam, which is attached via BGA or dual compression. The system is Telcordia qualified with over 10 years of proven reliability in the field. The Snap and Go assembly includes a fence for anchoring and an elastomeric boot for environmental protection. Avago's MicroPOD[™] is separable without desoldering. On the top side the integrated heat sink, spring and latch allow hand assembly without tools or hardware. Retention features in the fence engage the cap providing reliable compression force.

Samples are available now. Higher volumes off production tooling will be available in May of this year. Price lists are available upon request. Assembly PN is 11058c Rev 2.

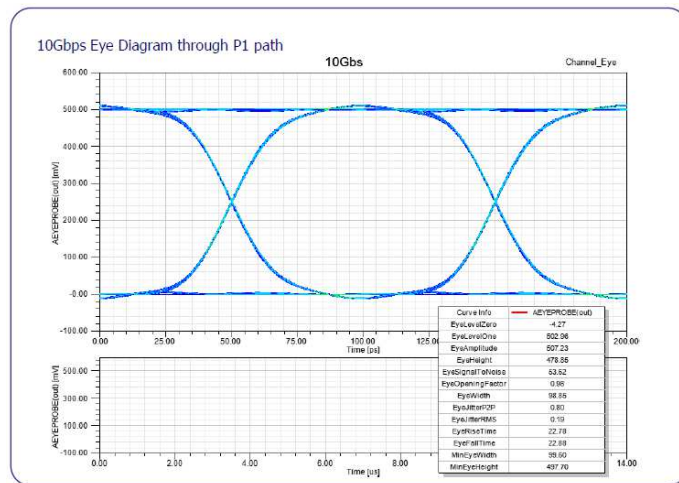
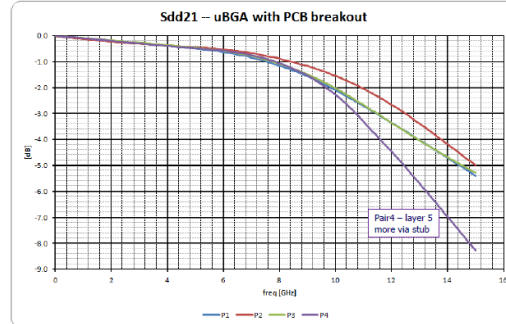
The cLGA[®] socket is fully qualified under the EIA-540BOAE and Telcordia GR-1217-CORE specifications. Reference the 'EIA / Telcordia Qualification Report' in the cLGA section of our website: www.interconsystems.com.

High Speed Electrical Performance

A complete electrical performance test report is available upon request.



Differential Insertion Loss



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¹ U.S. Patent numbers 6,176,707 and 6,217,342. Other patents pending.